



PRODUCT BULLETIN

Standard Flex

Single Layer
Flexible Circuit Interconnect

Layers

- 1-layer

Base Material

- Polyimide - 50 μ (.002") flame retardant (FR) or non-flame retardant polyester epoxy adhesive
- Polyester - 75 μ (.003") or 125 μ (.005") FR or non-FR polyester epoxy adhesive
- PEN - 50 μ (.002") non-FR polyester epoxy adhesive

Base Copper

- 1 oz/ft² - 35 μ (.0014")
- 2 oz/ft² - 70 μ (.0028")
- 3 oz/ft² - 105 μ (.0042")
- 4 oz/ft² - 140 μ (.0056")

Soldermask/Dielectric

- Screen Printed Ink
- Photoimaged coverlay
- Polyimide film - 25 μ (.001")
- Polyester film - 75 μ (.003")

Surface Finish

- Antitarnish
- *Shelcoat*[®] - OSP - organic solderability preservative
- Tin/lead - electroplated
- Tin/lead - Hot air solder leveled (HASL)
- Nickel/Gold - electroplated

Conductor Width and Space

- 1 oz/ft² - 35 μ (.0014") - .254 mm (.010") minimum
- 2 oz/ft² - 70 μ (.0028") - .305 mm (.012") minimum
- 3 oz/ft² - 105 μ (.0042") - .500 mm (.020") minimum
- 4 oz/ft² - 140 μ (.0056") - 1.0 mm (.040") minimum

Soldermask/Dielectric Definition

- See Sheldahl Standard Flexible Circuit Design Guideline

Design Capability

- Sheldahl has a extensive design capability. Design data and net lists can be input and output in a wide variety of standard industry formats

Prototype Capability

- Sheldahl has a fully staffed prototype facility that will provide prototypes in 1-3 weeks

